

## Specifications

|                                  |                                       |
|----------------------------------|---------------------------------------|
| Insulation Resistance:           | 1,000M min. at 100V DC                |
| Dielectric Withstanding Voltage: | 100V AC for 1 minute                  |
| Contact Resistance:              | 1 max. at 10mA/20mV max.              |
| Operating Temperature Range:     | -40°C to +150°C                       |
| Mating Cycles:                   | 10,000 insertions min.                |
| Pin Count:                       | 225 contact pins                      |
| Contact Force:                   | 25g to 35g per individual contact pin |

## Materials and Finish

Housing: Polyetherimide (PEI), glass-filled  
 Contacts: Beryllium Copper (BeCu)  
 Plating: Gold over Nickel



## Part Number (Details)

**IC264 - 225 01 - 1 - \*\* - MF**

Series No.

No. of Contact Pins

Design Number

NN: Without Positioning Pin #1, #2

NP: Without Positioning Pin #1, With Positioning Pin #2

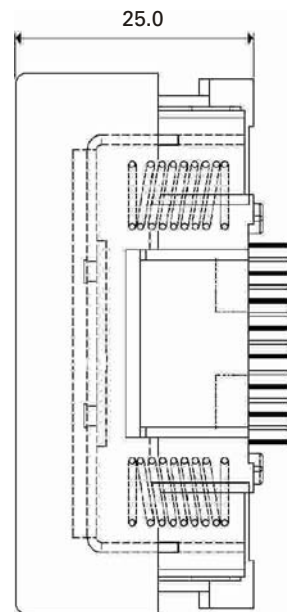
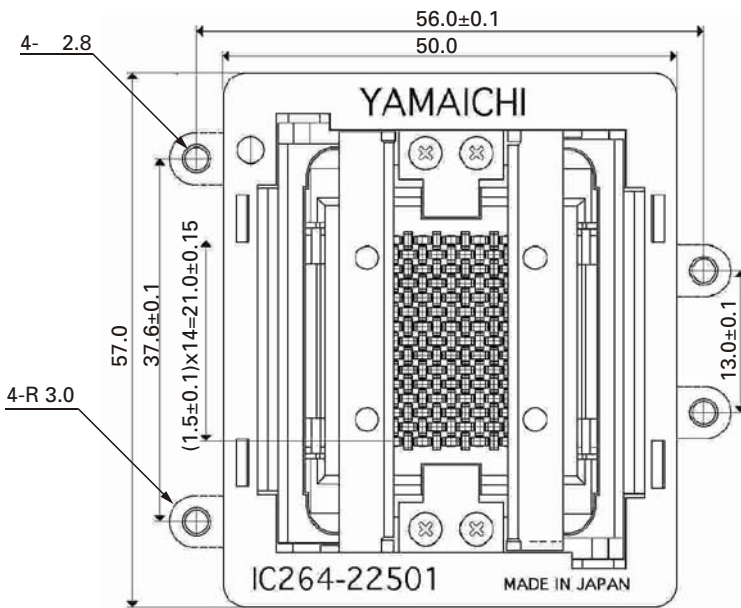
PN: With Positioning Pin #1, Without Positioning Pin #2

Blank: With Positioning Pin #1, #2

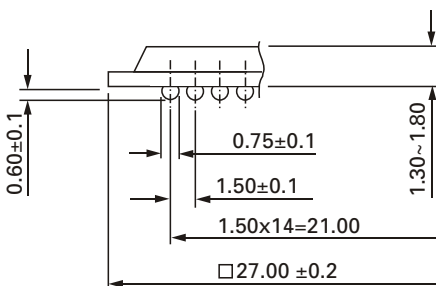
MF = Flanged

Unmarked = Not Flanged

## Outline Socket Dimensions



## Matching IC Dimensions



## Recommended PC Board Layout

IC264-22501-1-\*\*-\*\*

Top View from Socket

